General Description

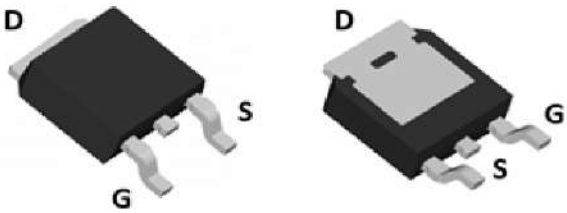
- Low $R_{DS(on)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Fast switching and soft recovery

Applications

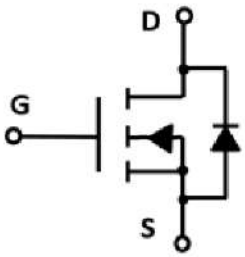
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

Product Summary

V_{DS}	100	V
$R_{DS(on),Typ}$@ V_{GS}=10 V	14	mΩ
I_D	45	A



TO-252



Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	100	V
Gate-source Voltage		V_{GS}	±20	V
Drain Current	T_C=25℃	I_D	45	A
	T_C=100℃		28.5	
Pulsed Drain Current [A]		I_{DM}	180	A
Avalanche energy [B]		E_{AS}	81	mJ
Total Power Dissipation [C]	Tc=25℃	P_D	72	W
	Tc=100℃		28.8	
Junction and Storage Temperature Range		T_J ,T_{STG}	-55～+150	℃

Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient [D]	t≤10S	$R_{\theta JA}$	15	20	℃/W
Thermal Resistance Junction-to-Ambient [D]	Steady-State		40	50	
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	1.35	1.7	

Electrical Characteristics (T_j=25℃ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}= 0V, I_D=250μA	100			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=100,V_{GS}=0V			1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}= ±20V, V_{DS}=0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}= V_{GS}, I_D=250μA	1	1.8	3	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	V_{GS}= 10V, I_D=20A		14	17	mΩ
		V_{GS}= 4.5V, I_D=20A		17	21.5	mΩ
Diode Forward Voltage	V_{SD}	I_S=20A,V_{GS}=0V			1.3	V
Maximum Body-Diode Continuous Current	I_S				45	A
Gate resistance	R_G	f= 1 MHz, Open drain		1		Ω
Dynamic Parameters						
Input Capacitance	C_{iss}	V_{DS}=50V,V_{GS}=0V,f=1MHZ		1135		pF
Output Capacitance	C_{oss}			399		
Reverse Transfer Capacitance	C_{rss}			18		
Switching Parameters						
Total Gate Charge	Q_g	V_{GS}=10V,V_{DS}=50V,I_D=25A		16		nC
Gate-Source Charge	Q_{gs}			5.6		
Gate-Drain Charge	Q_{gd}			2.4		
Reverse Recovery Chrage	Q_{rr}	I_F=20A, di/dt=100A/us		42		
Reverse Recovery Time	t_{rr}			39.8		ns
Turn-on Delay Time	$t_{D(on)}$	V_{GS}=10V, V_{DD}=50V,I_D=25A R_{GEN}=2.2Ω		39.2		
Turn-on Rise Time	t_r			11		
Turn-off Delay Time	$t_{D(off)}$			53.2		
Turn-off fall Time	t_f			15.8		

A. Repetitive rating; pulse width limited by max. junction temperature.
B. V_{DD}=50V, R_G=25Ω, L=0.5mH, I_{AS}=25A,.
C. Pd is based on max. junction temperature, using junction-case thermal resistance.
D. The value of RqJA is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with TA =25°C. The Power dissipation PDSM is based on R qJA t≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

Typical Performance Characteristics

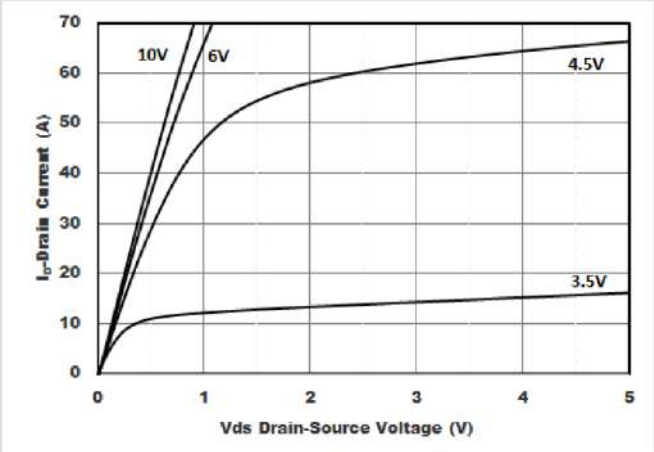


Figure1. Output Characteristics

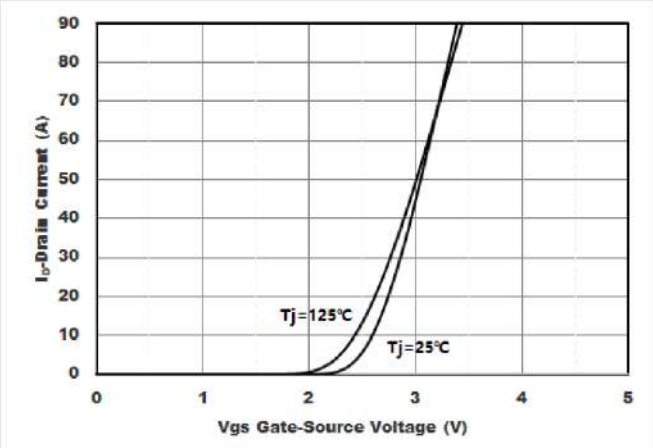


Figure2. Transfer Characteristics

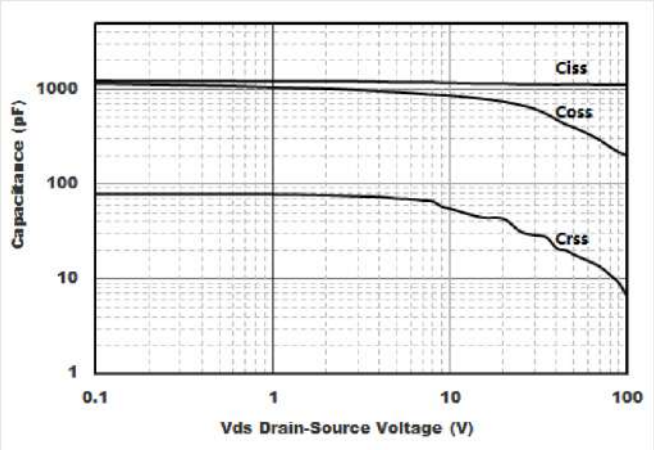


Figure3. Capacitance Characteristics

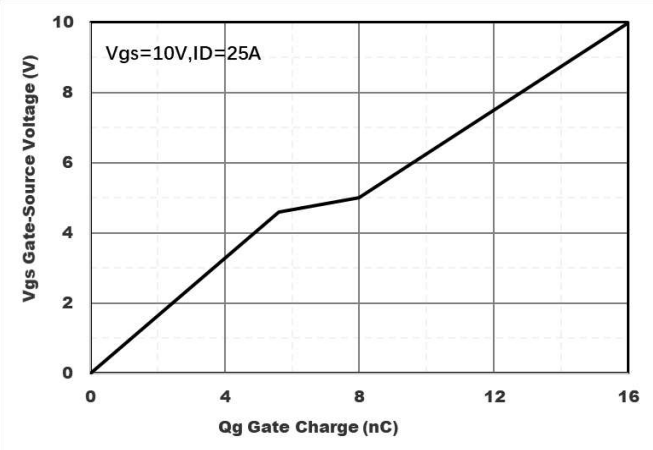


Figure4. Gate Charge

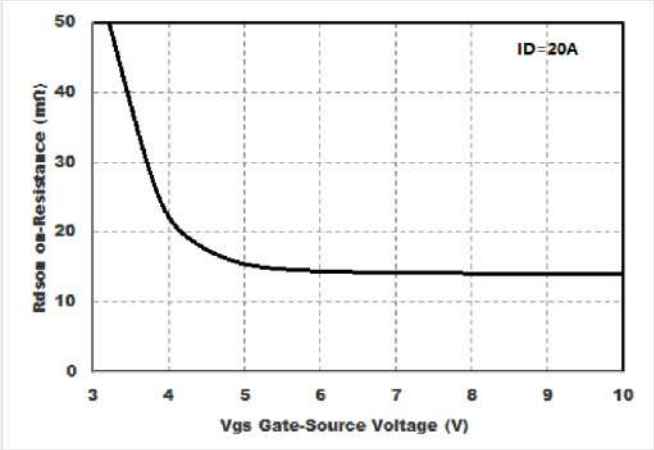


Figure5. **:** On-Resistance vs. Drain Current and Gate Voltage

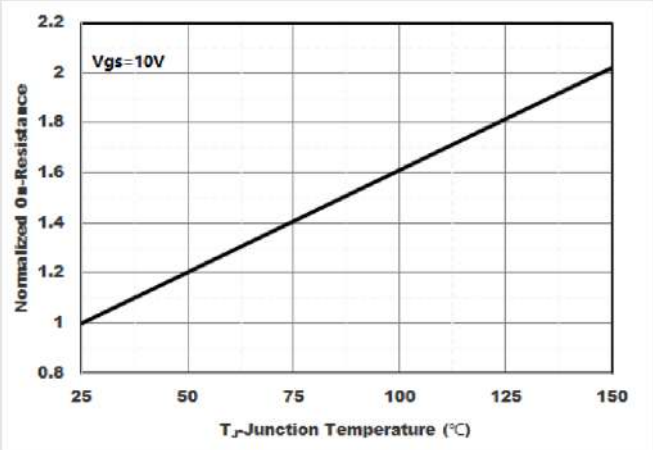


Figure6.Normalized On-Resistance

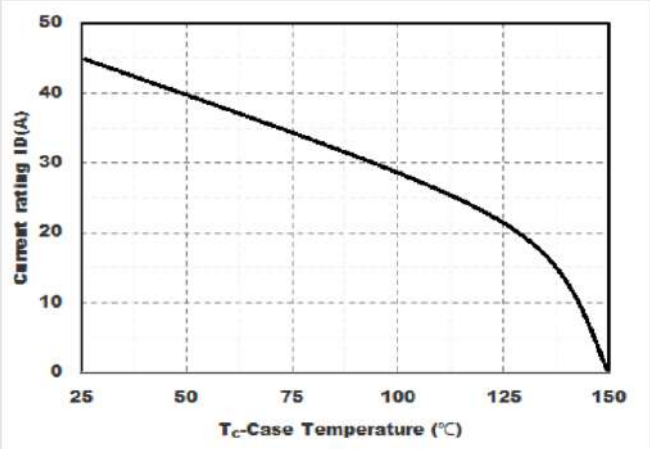


Figure7. Drain current

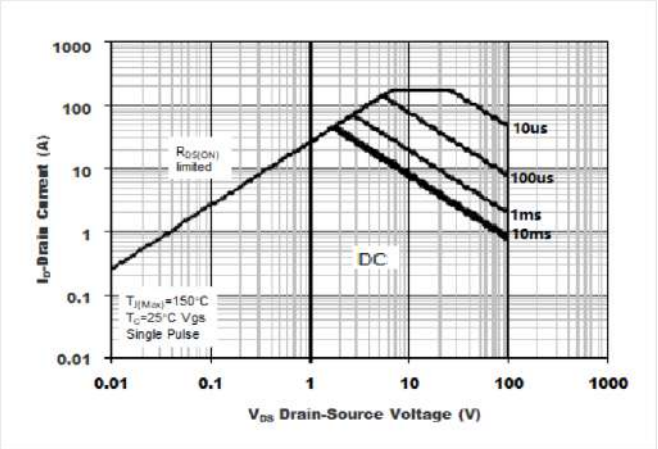


Figure8.Safe Operation Area

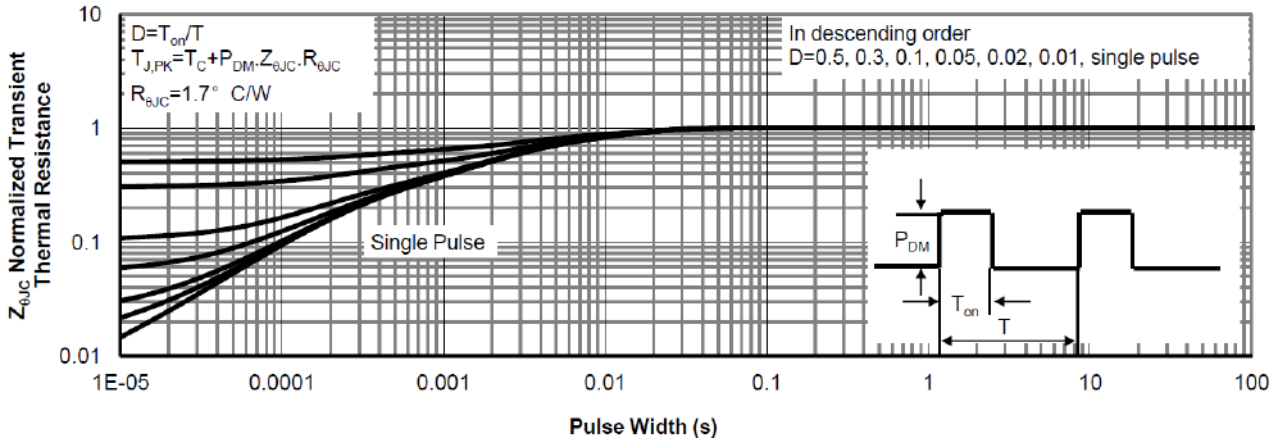
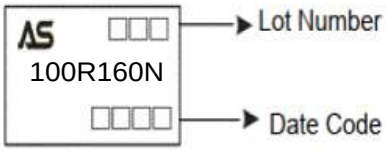


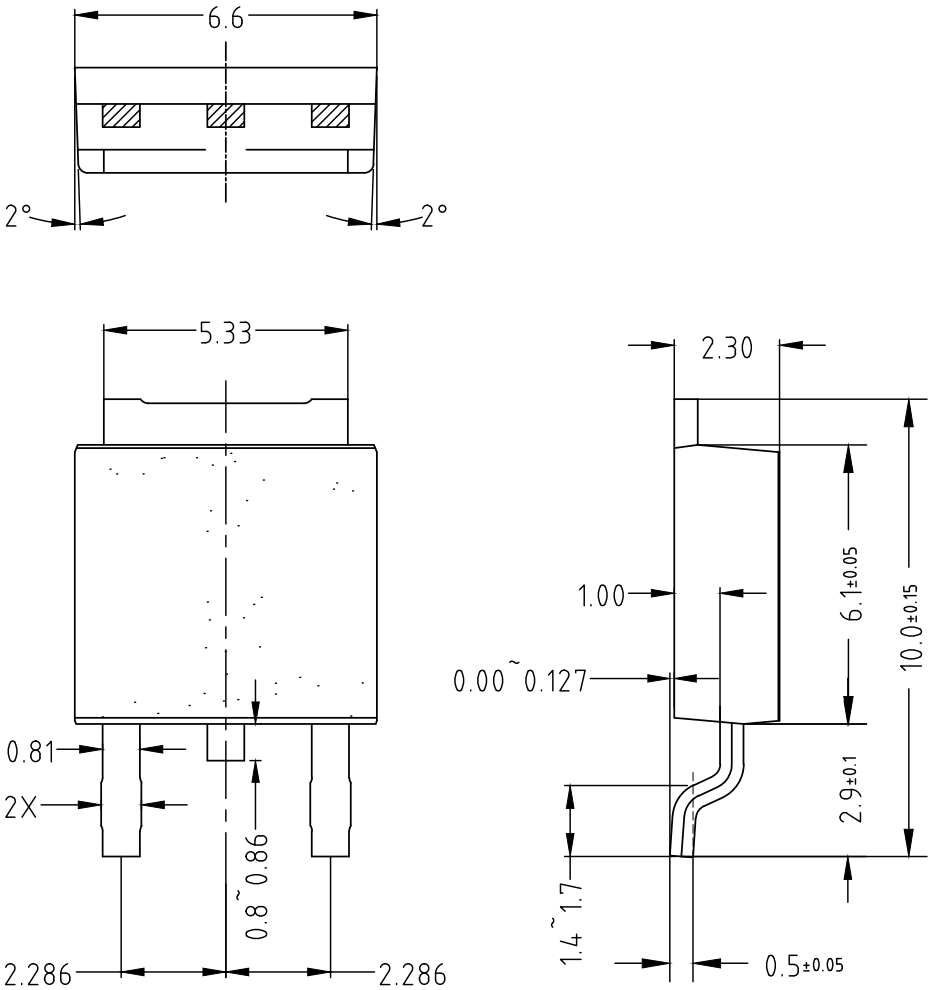
Figure9.Normalized Maximum Transient thermal impedance

Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM100R160NKQ-R	100R160N	TO-252	Tape&Reel	2500/Reel

PACKAGE	MARKING
TO-252	

TO-252


6.6
2°
2°
5.33
0.81
0.88~2X
0.8~0.86
2.286
2.286
2.30
1.00
0.00~0.127
6.1±0.05
10.0±0.15
2.9±0.1
1.4~1.7
0.5±0.05

IMPORTANT NOTICE

Xi'an Ascend Semiconductor incorporated MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Xi'an Ascend Semiconductor Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Xi'an Ascend Semiconductor Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Xi'an Ascend Semiconductor Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume .

all risks of such use and will agree to hold Ascendsemi Incorporated and all the companies whose products are represented on Xi'an Ascend Semiconductor Incorporated website, harmless against all damages.

Xi'an Ascend Semiconductor Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Xi'an Ascend Semiconductor Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Xi'an Ascend Semiconductor Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

www.ascendsemi.com